

FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MICRON.1824	APPLICATION NO. 09/973,854
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		APPLICANT Chopra et al	COPY OF PAPERS ORIGINALLY FILED
(USE SEVERAL SHEETS IF NECESSARY)		FILING DATE October 9, 2001	

U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)

FOREIGN PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)	
	A	Dinesh Chopra and Ian Ivar Suni, "An Optical Method for Monitoring Metal Contamination during Aqueous Processing of Silicon Wafers", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 5, May 1998, pp. 1688-1692.
	B	Dinesh Chopra, Ian Ivar Suni and Ahmed A. Bushaina, "Cu Dissolution from Si(111) into an SC-1 Process Solution", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 4, April 1998, pp. L60-61.
	C	Peter Singer, Editor-in-Chief, "Copper CMP: A Question of Tradeoffs", <i>Semiconductor International</i> , <a href="http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp">http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp</a> , May 2000, 11 pages.
	D	"The CMP Business Unit", Rodel Products, <a href="http://www.rodel.com/Products/CMP.asp">http://www.rodel.com/Products/CMP.asp</a> , 1998-2000, 13 pages.
	E	Kurt Hery and Dr. David P. Norwood, "Study of the Refractive Index Increment of Polyelectrolytes and Neutral Polymers", Southeastern Louisiana University, <a href="http://www.selu.edu/Academics/Arts&amp;Sciences/connections/journal1/k-hery/Hery.html">http://www.selu.edu/Academics/Arts&amp;Sciences/connections/journal1/k-hery/Hery.html</a> , 7 pages.
	F	Iqbal Ali and Sudipto R. Roy, "Pad conditioning in interlayer dielectric CMP", Texas Instruments, <a href="http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht">http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht</a> , June 1, 1997, 6 pages.
	G	"Chemical Mechanical Planarization (CMP)", S.C. Solutions, <a href="http://www.scsolutions.com/smp.html">http://www.scsolutions.com/smp.html</a> , 4 pages.

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EXAMINER <i>Spilaction</i>	DATE CONSIDERED 1/12/04
*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.	

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